

MK® DOPO-HQ

ED2312

Description

Chemical Name	6-(2,5-Dihydroxyphenyl)-6H-dibenz [c,e] [1,2] oxaphosphorine-6-oxide 10-(2,5-Dihydroxyphenyl)-10H-9-oxa-10-phospha-phenantbrene-10-Oxide
CAS Number	99208-50-1
Chemical Structure	
Chemical Formula	C ₁₈ H ₁₃ O ₄ P
Molecular Weight	324.28

Specification

Appearance	White powder and granule
Assay	99% min
Melting Point	245°C~253°C
Specific Gravity	1.38~1.40 (25°C)
Solubility (g/L@20°C)	
Slightly Soluble in	Methanol, Ethanol, Isopropanol, Acetone, MEK, THF, DMF
InSoluble in	Water
Packing	Net 20kg /box

Application

MK DOPO-HQ is a new phosphate, halogen-free Flame retardant, for high quality epoxy resin
Such as PCB, to replace TBBA, or adhesive for semiconductor, PCB, LED and so on.
Intermediate for synthesis of reactive Flame retardant.

For Example: Various amounts of DOPO-HQ were added to phenol formaldehyde novolac
As a curing agent for cresol formaldehyde novolac epoxy resin to determine the
Flame-retardant effect of phosphorus.

It serves as stabilizers and flame retardant for polymers. It also can be copolymerized in
Epoxy, polyester, polyurethane resins to exhibit superior stabilization and flame
Retardant with resistance to solvent extraction, volatility and blooming. The max
Thermo-decomposition rate of the DOPO-HQ is 350°C.